MC100EL30

5V ECL Triple D Flip-Flop with Set and Reset

The MC100EL30 is a triple master–slave D flip–flop with differential outputs. Data enters the master latch when the clock input is LOW and transfers to the slave upon a positive transition on the clock input.

In addition to a common Set input individual Reset inputs are provided for each flip flop. Both the Set and Reset inputs function asynchronous and overriding with respect to the clock inputs.

Features

- 1200 MHz Minimum Toggle Frequency
- 450 ps Typical Propagation Delays
- ESD Protection: >2 kV Human Body Model
- The 100 Series Contains Temperature Compensation.
- PECL Mode Operating Range:
  V_{CC} = 4.2 V to 5.7 V with V_{EE} = 0 V
- NECL Mode Operating Range:
  V_{CC} = 0 V with V_{EE} = −4.2 V to −5.7 V
- Internal Input 75 kΩ Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Pb = Level 1
                      Pb−Free = Level 3
  For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−0 @ 0.125 in,
  Oxygen Index: 28 to 34
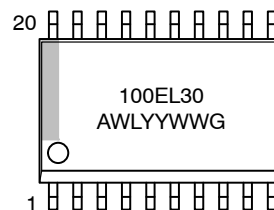- Transistor Count = 347 devices
- Pb−Free Packages are Available*

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http://onsemi.com
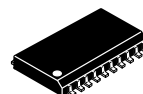
SO−20 WB
DW SUFFIX
CASE 751D

MARKING DIAGRAM*

100EL30
AWLYYWWG

|	
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC100EL30
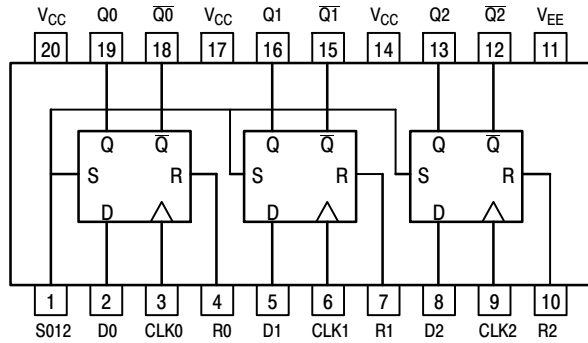
Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagram and Pinout: 20-Lead SOIC (Top View)

Table 1. PIN DESCRIPTION

Pin	Function
D0–D2	ECL Data Inputs
R0–R2	ECL Reset Inputs
CLK0–CLK2	ECL Clock Inputs
S012	ECL Common Set Input
Q0–Q2; $\overline{Q0}$–$\overline{Q2}$	ECL Differential Data Outputs
V_{CC}	Positive Supply
V_{EE}	Negative Supply

Table 2. FUNCTION TABLE

R*	S*	D*	CLK*	Q	$\overline{Q}$
L	L	L	Z	L	H
L	L	H	Z	H	L
H	L	X	X	L	H
L	H	X	X	H	L
H	H	X	X	Undef	Undef

Z = Low-to-High Transition
X = Don't Care
*Pin will default low when left open.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 to 0 −6 to 0	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction–to–Ambient)	0 lfpm 500 lfpm	SOIC–20 SOIC–20	90 60	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction–to–Case)	Standard Board	SOIC–20	30 to 35	°C/W
T_{sol}	Wave Solder Pb Pb–Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. PECL DC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= 0.0 V (Note 1)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	62		55	62		55	64	mA
V_{OH}	Output HIGH Voltage (Note 2)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 2)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
V_{IH}	Input HIGH Voltage	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW Voltage	3190		3525	3190		3525	3190		3525	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.8 V / −0.5 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.

Table 5. NECL DC CHARACTERISTICS V_{CC}= 0.0 V; V_{EE}= −5.0 V (Note 3)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	62		55	62		55	64	mA
V_{OH}	Output HIGH Voltage (Note 4)	−1085	−1005	−880	−1025	−955	−880	−1025	−955	−880	mV
V_{OL}	Output LOW Voltage (Note 4)	−1830	−1695	−1555	−1810	−1705	−1620	−1810	−1705	−1620	mV
V_{IH}	Input HIGH Voltage	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage	−1810		−1475	−1810		−1475	−1810		−1475	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.8 V / −0.5 V.
4. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.

Table 6. AC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= 0.0 V   or V_{CC}= 0.0 V; V_{EE}= −5.0 V (Note 5)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency	1.0			1.2			1.2			GHz
t_{PLH} t_{PHL}	Propagation Delay to Output CLK, S, R	550		800	570		820	590		840	ps
t_S t_H	Setup Time Hold Time	150 200	0 100		150 200	0 100		150 200	0 100		ps
t_{RR}	Set/Reset Recovery	400	200		400	200		400	200		ps
t_{PW}	Minimum Pulse Width CLK Set, Reset	400 650			400 650			400 650			ps
t_{JITTER}	Cycle−to−Cycle Jitter		TBD			TBD			TBD		ps
t_r t_f	Output Rise/Fall Times Q (20% − 80%)	280		550	280	450	550	280		550	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. V_{EE} can vary +0.8 V / −0.5 V.
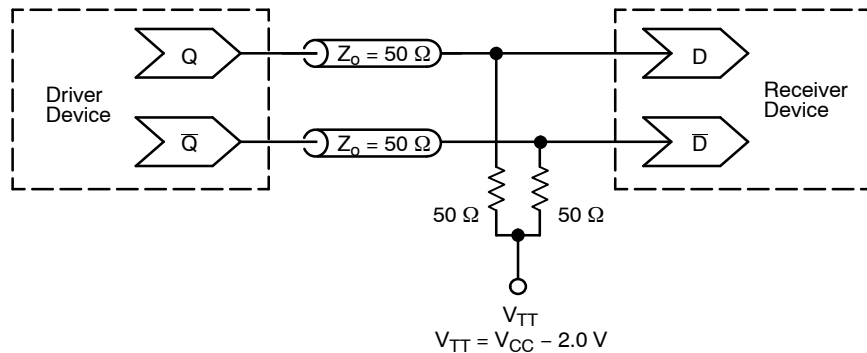
Figure 2. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D − Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Package†
MC100EL30DW	SOIC−20	38 Units / Rail
MC100EL30DWG	SOIC−20 (Pb−Free)	38 Units / Rail
MC100EL30DWR2	SOIC−20	1000 / Tape & Reel
MC100EL30DWR2G	SOIC−20 (Pb−Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SO−20 WB
DW SUFFIX
CASE 751D−05
ISSUE G
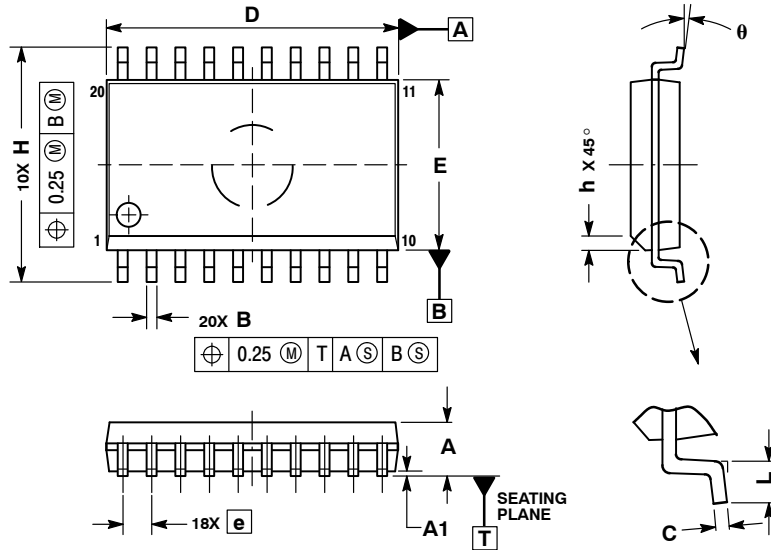
NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °

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